Ref	Hits	Search Query	DBs	Default	Plurals	Time Stamp
#	1116	- Control Query		Operator	, idiais	Time Starrip
L1	0	(flip adj chip) and (functional adj solder adj bumps)	USPAT	OR	ON	2005/04/26 16:02
L2	0	(flip adj chip) and (anchoring adj solder adj bumps)	USPAT	OR	ÓN	2005/04/26 16:03
L3	0	(flip adj chip) and (anchoring adj solder adj bump)	USPAT	OR	ON	2005/04/26 16:05
L4	0	(flip adj chip) and (solder adj bump)and (emty adj spaces)	USPAT	OR	ON	2005/04/26 16:04
L5	0	(flip adj chip) and GBA and (shear adj stress) and (cyclic adj temperature)	USPAT	OR	ON.	2005/04/26 16:06
L6	0	(flip adj chip) and GBA and (shear adj stress) and temperature	USPAT .	OR	ON	2005/04/26 16:06
L7	. 128	(flip adj chip)and (shear adj stress) and temperature	USPAT	OR	ON	2005/04/26 16:12
L8	3	(flip adj chip)and (shear adj stress) and temperature and spaces and solder and bump and anchor	USPAT	OR	ON	2005/04/26 16:29
L9	78	(flip adj chip)and (shear adj stress) and temperature and (solder adj ball)	USPAT	OR	ON	2005/04/26 16:13
L10	0	(flip adj chip)and (shear adj stress) and temperature and (solder adj ball) and (emty adj spaces)	USPAT	OR	ON	2005/04/26 16:13
L11	0	(flip adj chip)and (shear adj stress) and temperature and (solder adj ball) and space and anchor and functional	USPAT	OR	ON	2005/04/26 16:14
L12	0	(flip adj chip)and (shear adj stress) and temperature and (solder adj ball) and space and anchor	USPAT	OR	ON	2005/04/26 16:15
L13	1	(flip adj chip)and (shear adj stress) and temperature and (solder adj ball) and anchor	USPAT	OR	ON	2005/04/26 16:27
L14	1	"6479900".PN.	USPAT; USOCR	OR	ON	2005/04/26 16:24
L15	1	"6462425".PN.	USPAT; USOCR	OR	ON	2005/04/26 16:25
L16	1	"6434017".PN.	USPAT; USOCR	OR	ON	2005/04/26 16:25
L17	1	"6404051".PN.	USPAT; USOCR	OR	ON	2005/04/26 16:26

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L18	1	"5036383".PN.	USPAT; USOCR	OR	ON	2005/04/26 16:26
L19	1	"4742023".PN.	USPAT; USOCR	OR	ON	2005/04/26 16:27
L20	1	("6686605").PN.	USPAT	OR	OFF	2005/04/26 16:29
L21	1	20 and (flip or chip or solder or bump or anchor or anchoring or PCB or BGA or shear or stress or cyclic or temperature or stabilizing or function or functional or width or pad or emty or spaces or space or lead or copper or silver or nickel)	USPAT	OR	ON	2005/04/26 16:33
L22	1	13 and (flip or chip or solder or bump or anchor or anchoring or PCB or BGA or shear or stress or cyclic or temperature or stabilizing or function or functional or width or pad or emty or spaces or space or lead or copper or silver or nickel)	USPAT	OR	ON	2005/04/26 16:51
L23	2859	438/106	USPAT	OR	ON	2005/04/26 16:52
L24	1526	438/107	USPAT	OR	ON .	2005/04/26 16:52
L25	2086	438/108	USPAT	OR	ON	2005/04/26 16:52
L26	844	438/109	USPAT	OR	ON	2005/04/26 16:52
L27	835	438/110	USPAT	OR	ON	2005/04/26 16:52
L28	1160	438/455	USPAT	OR	ON	2005/04/26 16:52
L29	1698	438/612	USPAT	OR	ON	2005/04/26 16:52
L30	1560	438/613	USPAT	OR .	ON	2005/04/26 16:52